External Visual Inspection per Mil-Std-883 TM 2009
Course Outline (1/2 DAY)

Chipouts in Glass to Metal Seals

This course covers the visual inspection criteria for hermetic packaged microelectronic devices and similar devices and a review of typical plastic package defects in accordance with best commercial practices. Color photographs of actual production defects are reviewed and discussed in detail. The students are exposed to a variety of defects and the instructor explains why the defects are critical to the reliability of the end product.

- Understand what to look for as part of external visual inspection (TM 2009)
- Learn how to interpret and apply traditional Mil Spec visual inspection requirements
- Review products/defects “hands-on” in the Classroom as arranged

External Visual Inspection per TM 2009

- Weld and Seal defects
- Glass and ceramic feedthru defects e.g. meniscus cracking
- Package marking and pin/lead defects
- Inspection Criteria for Microelectronic Packages and Covers
- Foreign Material Identification and Contamination Control

Review applicable criteria in JESD 9B

Plastic Package Defects

Summary and Review Q&A Session
Student Certification Test
Student Feedback and Course Critique